External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0	0.66	0.07
	Doped silicon	Silicon (Si)	7440-21-3	0.47	99.34	9.93
			Subtotal	0.47	100	10
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.1	100.0	2.04
			Subtotal	0.1	100	2.04
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.11
	Copper alloy	Iron (Fe)	7439-89-6	0.02	0.1	0.36
	Copper alloy	Copper (Cu)	7440-50-8	16.8	99.87	358.53
			Subtotal	16.83	100	359
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.36
	Copper alloy	Iron (Fe)	7439-89-6	0.06	0.1	1.2
	Copper alloy	Copper (Cu)	7440-50-8	56.14	99.87	1198.44
			Subtotal	56.22	100	1200
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0	0.1	0.09
	Copper alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.86	91.6	82.44
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04	0.9	0.81
	Copper alloy	Molybdenum (Mo)	7439-98-7	0.3	7.0	6.3
	Copper alloy	Manganese (Mn)	7439-96-5	0.02	0.4	0.36
			Subtotal	4.22	100	90
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.08	5.0	1.67
	Lead alloy	Silver (Ag)	7440-22-4	0.04	2.5	0.83
	Lead alloy	Lead (Pb)	7439-92-1	1.44	92.5	30.8
			Subtotal	1.56	100	33.3
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.55	8.7	33.06
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	2.85	16.0	60.8
	Filler	Silica fused	60676-86-0	13.35	75.0	285
	Carbon Black	Carbon black	1333-86-4	0.05	0.3	1.14
			Subtotal	17.8	100	380
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.26	100.0	27
			Subtotal	1.26	100	27
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.08	5.0	1.67
	Lead alloy	Silver (Ag)	7440-22-4	0.04	2.5	0.83
	Lead alloy	Lead (Pb)	7439-92-1	1.44	92.5	30.8
			Subtotal	1.56	100	33.3
			Total	100.02	100	2134.64

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